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For immediate release

Ventec's Martin Cotton to unveil industry's most advanced Ultra-Low Dk PCB Materials for High-Speed Low-Loss Applications at DesignCon 2017

January 10, 2017 – Ventec International, a world leader in the production of polyimide & high reliability epoxy laminates and prepregs, is participating at the 2017 DesignCon show in Santa Clara, CA, USA from 31st January to 2nd February as both an exhibitor on booth #118 and technical presenter. The presentation will unveil the industry's most advanced ultra-low Dk PCB materials for high-speed low-loss applications.

Ventec will be participating at DesignCon 2017, the premier conference for chip, board, and systems design engineers, on booth #118 and has specifically chosen the event as the ideal platform to unveil the industry's latest advances in PCB materials for high-speed low-loss applications. Ventec's Martin Cotton (Director - OEM Technology Marketing) and Bill Wang (Technical Director) will be presenting their paper titled "Ultra-Low Dk PCB Materials for High-Speed Low-Loss Applications" in Ballroom F on Wednesday, 1st February at 8:00am.

The technical presentation will demonstrate how lower losses and lower system power requirements are realized by using an ultra-low Dk material with Dk values between 2.3 and 2.8. "By lowering the material Dk to ultra-low levels using FR4 processes, the delicate balance of performance and cost is achieved", said Martin Cotton. "Higher layer counts on backplanes, daughter cards and hand-held's are achieved in a smaller footprint by having smaller layer to layer separation without sacrificing trace width. Having potentially wider traces produces lower resistance in the signal path" he continues. "Combining ultra-low Dk with a low Df of 0.002 to 0.004, produces an alternative to ever smaller traces and higher power requirements."

For more information about Ventec's solutions and the company's wide variety of products, please visit www.ventecclaminates.com and/or download the Ventec APP.

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About Ventec International

With volume manufacturing facilities and HQ in Suzhou China, Ventec International specializes in advanced copper clad glass reinforced and metal backed substrates for the PCB industry. With distribution locations and quick-turn CCL manufacturing sites in both the US and Europe, Ventec International is a premier supplier to the Global PCB industry. For more information, visit www.ventec laminates.com.

About DesignCon

DesignCon is the world's premier conference for chip, board, and systems design engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley and remains the largest gathering of chip, board, and systems designers in the country. This three-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: designcon.com. DesignCon is organized by UBM Americas, a part of UBM plc (UBM.L), an Events First marketing and communications services business. For more information, visit www.ubmamericas.com.

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